

In the claims:

Amend claim 1 as follows:

1. (Amended) A device comprising:

a package having a cavity therein;

a semiconductor device in said cavity, said semiconductor device having at least one optical receiver and/or transmitter adjacent a surface of said semiconductor device facing away from said package; and

a thin film overlay electrically connecting bond pads on said semiconductor device to electrically conductive pads on a layer of said thin film overlay facing away from said semiconductor device.

Rewrite claim 6 in independent form as follows:

6. A device comprising:

a package having a cavity therein;

a semiconductor device in said cavity, said semiconductor device having at least one optical receiver and/or transmitter adjacent a surface of said semiconductor device facing away from said package; and

a thin film overlay electrically connecting bond pads on said semiconductor device to electrically conductive pads on a layer of said thin film overlay facing away from said semiconductor device;

wherein said thin film overlay includes a hole between said optical receiver and/or transmitter on said semiconductor device and said layer of said thin film overlay facing away from said semiconductor device;